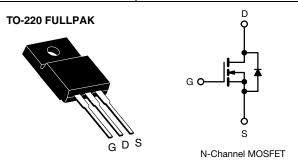


Vishay Siliconix

E Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.125			
Q _g max. (nC)	130			
Q _{gs} (nC)	15			
Q _{gd} (nC)	39			
Configuration	Single			



FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
 - LED lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- · Battery chargers
- · Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION			
Package	TO-220 FULLPAK		
Lead (Pb)-free and Halogen-free	SiHF30N60E-GE3		
Lead (Pb)-free	SiHF30N60E-E3		

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	600	V
Gate-Source Voltage			V_{GS}	± 30	V
Continuous Drain Current (T _{.I} = 150 °C) ^d	\/ at 10 \/	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		29	
Continuous Drain Current (1) = 150°C)	V _{GS} at 10 V	T _C = 100 °C	I _D	18	Α
Pulsed Drain Current ^a			I _{DM}	76	
Linear Derating Factor				0.29	W/°C
Single Pulse Avalanche Energy b			E _{AS}	690	mJ
Maximum Power Dissipation			P_{D}	37	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope $V_{DS} = 0 \text{ V to } 80 \text{ % } V_{DS}$		dV/dt	70	V/ns	
Reverse Diode dV/dt ^e			18	V/115	
Soldering Recommendations (Peak temperature) c	mmendations (Peak temperature) c for 10 s			300	°C
Mounting Torque M3 screw				0.6	Nm

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 28.2 \,\text{mH}$, $R_q = 25 \,\Omega$, $I_{AS} = 7 \,\text{A}$.
- c. 1.6 mm from case.
- d. Limited by maximum junction temperature.
- e. $I_{SD} \le I_D$, $d\dot{l}/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.4	G/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				l		•	·
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 250 μA	-	0.64	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	2.8	4.0	V
Cata Cauraa Laglaga			V _{GS} = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zoro Coto Voltago Drain Current		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	μА
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 600 \	/, V _{GS} = 0 V, T _J = 150 °C	-	-	100	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A	-	0.104	0.125	Ω
Forward Transconductance ^a	9 _{fs}	V _D	_S = 8 V, I _D = 3 A	-	5.4	-	S
Dynamic		•			•	•	
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	2600	-	
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	138	-	
Reverse Transfer Capacitance	C_{rss}		f = 1.0 MHz	-	3	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	98	-	pF
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	346	-	
Total Gate Charge	Qg			-	85	130	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 15 A, V_{DS} = 480 V$	-	15	-	nC
Gate-Drain Charge	Q _{gd}			-	39	-	1 '
Turn-On Delay Time	t _{d(on)}			-	19	40	
Rise Time	t _r	Vpp = 380 V, lp = 15 A.		-	32	65	no
Turn-Off Delay Time	t _{d(off)}	V _{DD} = 380 V, I _D = 15 A,		63	95	ns	
Fall Time	t _f			-	36	75	1
Gate Input Resistance	R_{g}	f = 1	MHz, open drain	-	0.63	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	bol	-	-	29	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	65	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 15 A, V _{GS} = 0 V		_	-	1.3	V
Body Diode Reverse Recovery Time	t _{rr}			-	402	605	ns
Body Diode Reverse Recovery Charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 15 \text{A},$		7	15	μC	
Reverse Recovery Current	I _{RRM}	dl/dt = 100 A/µs, V _R = 20 V			32	65	A

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

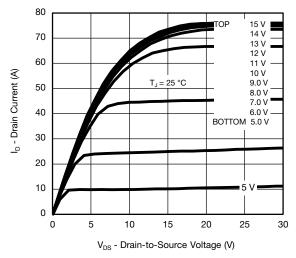


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

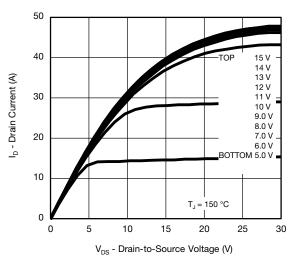


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

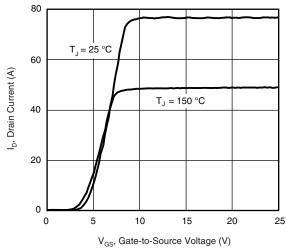


Fig. 3 - Typical Transfer Characteristics

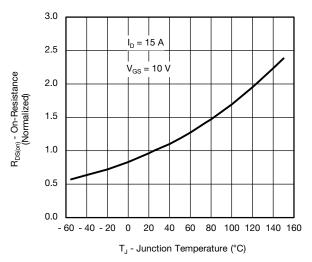


Fig. 4 - Normalized On-Resistance vs. Temperature

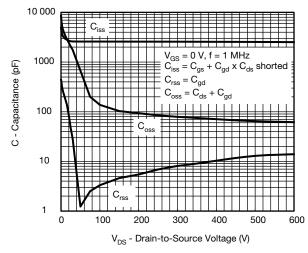


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

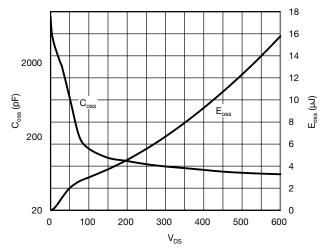


Fig. 6 - Coss and Eoss vs. VDS



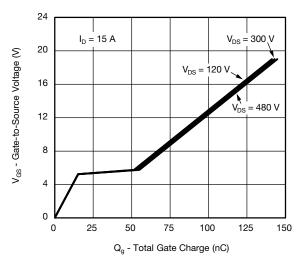


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

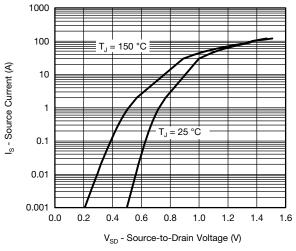


Fig. 8 - Typical Source-Drain Diode Forward Voltage

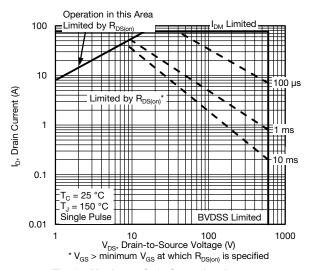


Fig. 9 - Maximum Safe Operating Area

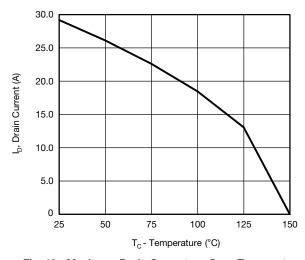


Fig. 10 - Maximum Drain Current vs. Case Temperature

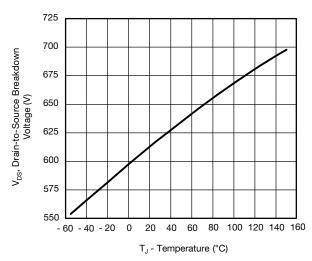


Fig. 11 - Temperature vs. Drain-to-Source Voltage



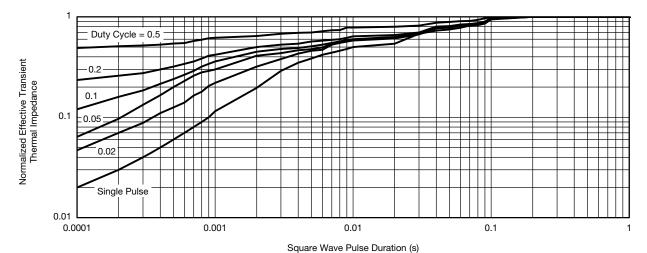


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

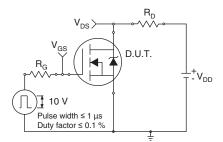


Fig. 13 - Switching Time Test Circuit

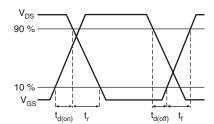


Fig. 14 - Switching Time Waveforms

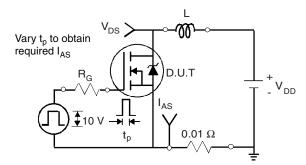


Fig. 15 - Unclamped Inductive Test Circuit

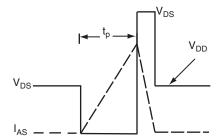


Fig. 16 - Unclamped Inductive Waveforms

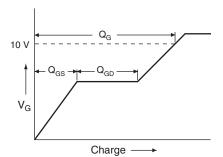


Fig. 17 - Basic Gate Charge Waveform

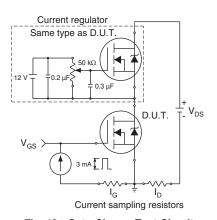
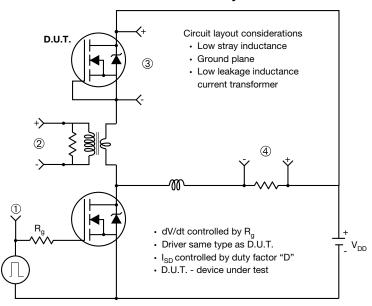


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



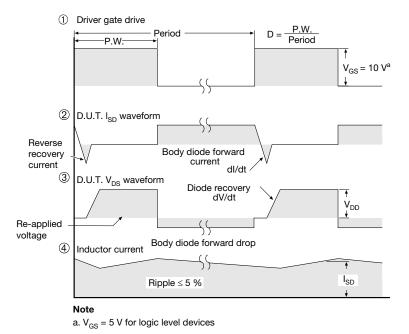


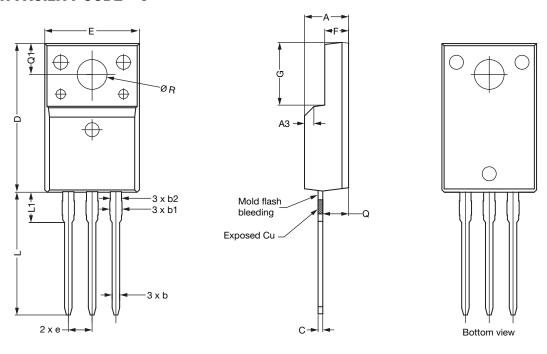
Fig. 19 - For N-Channel

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Vishay Siliconix

TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9

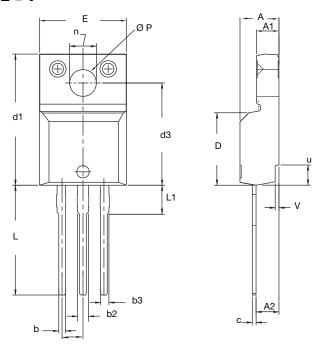


		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
Α	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



OPTION 2: FACILITY CODE = Y



	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
Е	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

ECN: E19-0180-Rev. D, 08-Apr-2019

DWG: 5972

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
- 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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